



ProLight PG1A-1Dxx 1W Power LED Technical Datasheet Version: 4.0

Features

- High flux per LED
- Various colors
- Good color uniformity
- Moisture senstivity level JEDEC 2a
 4 week floor life without reconditioning
- Low-temp. & lead free reflow soldering
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV
- Superior ESD protection

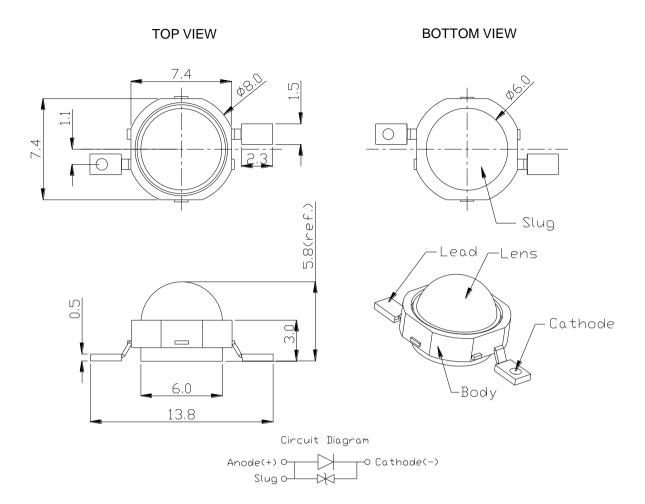
Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

ProLight

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Emitter Mechanical Dimensions

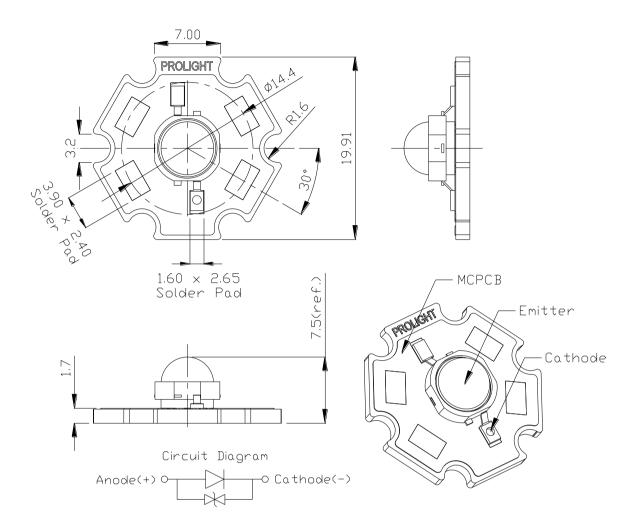


Notes:

- 1. The cathode side of the device is denoted by a hole in the lead frame.
- 2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not bend the leads of the LED, otherwise it will damage the LED.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

^{*}The appearance and specifications of the product may be modified for improvement without notice.

Star Mechanical Dimensions



Notes:

- 1. Slots in aluminum-core PCB for M3 or #4 mounting screw.
- 2. Electrical interconnection pads labeled on the aluminum-core PCB with "+" and "-" to denote positive and negative, respectively. All positive pads are interconnected, as are all negative pads, allowing for flexibility in array interconnection.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 350mA, T_J = 25°C

Radiation	Color	Part N	umber	Lumious Flux Φ_V (lm)	
Pattern	Color	Emitter	Star	Minimum	Typical
	White	PG1A-1DWE	PG1A-1DWS	87.4	123
	Warm White	PG1A-1DVE	PG1A-1DVS	87.4	118
	Red	PG1A-1DRE	PG1A-1DRS	39.8	47
Dome	Amber	PG1A-1DAE	PG1A-1DAS	39.8	53
	Green	PG1A-1DGE	PG1A-1DGS	58.9	78
	Cyan	PG1A-1DCE	PG1A-1DCS	58.9	68
	Blue	PG1A-1DBE	PG1A-1DBS	13.9	21

[•] ProLight maintains a tolerance of ± 10% on flux and power measurements.

Electrical Characteristics at 350mA, T_J = 25°C

	Fo	orward Voltage V _F	(V)	Thermal Resistance Junction to	Thermal Resistance Junction to
Color	Min.	Тур.	Max.	Slug (°C/W)	Board (°C/W)
White	2.85	3.4	4.1	10	13
Warm White	2.85	3.4	4.1	10	13
Red	1.75	2.2	3.0	10	13
Amber	1.75	2.2	3.0	10	13
Green	2.85	3.4	4.1	10	13
Cyan	2.85	3.4	4.1	10	13
Blue	2.85	3.4	4.1	10	13

ullet ProLight maintains a tolerance of \pm 0.1 for Voltage measurements.

Optical Characteristics at 350mA, $T_J = 25$ °C

Color		ninant Wavelengtl olor Temperature	= '	Total included Angle (degrees)	Viewing Angle (degrees)
Color	Min.	Тур.	Max.	$\theta_{0.90V}$	2 θ _{1/2}
White	4100 K	5500 K	10000 K	90	70
Warm White	2700 K	3300 K	4100 K	90	70
Red	613.5 nm	623 nm	631 nm	90	70
Amber	587 nm	592 nm	597 nm	90	70
Green	515 nm	525 nm	535 nm	90	70
Cyan	495 nm	505 nm	515 nm	90	70
Blue	455 nm	465 nm	475 nm	90	70

ullet ProLight maintains a tolerance of \pm 1nm for dominant wavelength measurements.

[•] Please do not drive at rated current more than 1 second without proper heat sink.

 $[\]bullet$ ProLight maintains a tolerance of $\pm\,5\%$ for CCT measurements.

Absolute Maximum Ratings

Parameter

White/Warm White/ Red/Amber/Green/Cyan/Blue

		_
DC Forward Current (mA)	350	
Peak Pulsed Forward Current (m/	500 (less than 1/10 duty cycle@1KHz)	
Average Forward Current (mA)	350	
ESD Sensitivity	±4000V (Class III)	
(HBM per MIL-STD-883E Method 3015.7)	±4000 (Class III)	
LED Junction Temperature (°C)	120°C	
Operating Board Temperature	-40°C - 105°C	
at Maximum DC Forward Current	-40 C - 103 C	
Storage Temperature	-40°C - 120°C	
Soldering Temperature	235°C	
Allowable Reflow Cycles	3	
Reverse Voltage	Not designed to be driven in reverse bias	

Photometric Luminous Flux Bin Structure

Color	Bin Code	Minimum Photometric Flux (lm)	Maximum Photometric Flux (Im)	Available Color Bins
	U1	87.4	99.6	All
White	U2	99.6	113.6	All
vviiite	V1	113.6	129.5	All
	V2	129.5	147.7	[1]
	U1	87.4	99.6	All
Warm White	U2	99.6	113.6	All
waiiii wiiile	V1	113.6	129.5	All
	V2	129.5	147.7	[1]
Red	R	39.8	51.7	All
Reu	S1	51.7	58.9	[1]
	R	39.8	51.7	All
Amber	S1	51.7	58.9	[1]
	S2	58.9	67.2	[1]
	S2	58.9	67.2	All
Green	T1	67.2	76.6	All
Green	T2	76.6	87.4	All
	U1	87.4	99.6	[1]
	S2	58.9	67.2	All
Cyan	T1	67.2	76.6	All
	T2	76.6	87.4	[1]
	М	13.9	18.1	[1]
Blue	N	18.1	23.5	A, 1 ^[1]
	Р	23.5	30.6	[1]

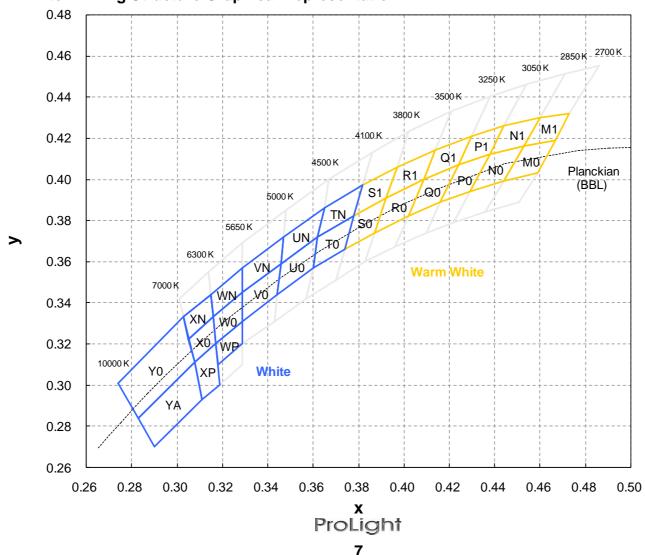
[•] ProLight maintains a tolerance of ± 10% on flux and power measurements.

[•] The flux bin of the product may be modified for improvement without notice.

^{• &}lt;sup>[1]</sup> The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Color Bin

White and Warm White Binning Structure Graphical Representation



Color Bins

White Bin Structure

Bin Code	х	у	Typ. CCT (K)	Bin Code	х	у	Typ. CCT (K)
	0.378	0.382			0.329	0.345	
T0	0.374	0.366	4300	WN	0.316	0.333	5970
10	0.360	0.357	4300	VVIN	0.315	0.344	3370
	0.362	0.372			0.329	0.357	
	0.382	0.397			0.329	0.331	
TN	0.378	0.382	4300	WP	0.329	0.320	5970
IIN	0.362	0.372	4300	VVI	0.318	0.310	3970
	0.365	0.386			0.317	0.320	
	0.362	0.372			0.308	0.311	
U0	0.360	0.357	4750	X0	0.305	0.322	6650
00	0.344	0.344	4730	Λ	0.316	0.333	0030
	0.346	0.359			0.317	0.320	
	0.365	0.386			0.305	0.322	
UN	0.362	0.372	4750	XN	0.303	0.333	6650
ON	0.346	0.359	4730	AIN	0.315	0.344	0030
	0.347	0.372			0.316	0.333	
	0.329	0.331			0.308	0.311	
V0	0.329	0.345	5320	XP	0.317	0.320	6650
VO	0.346	0.359	5520	ΛΓ	0.319	0.300	0030
	0.344	0.344			0.311	0.293	
	0.329	0.345			0.308	0.311	
VN	0.329	0.357	5320	Y0	0.283	0.284	8000
VIN	0.347	0.372	3320	10	0.274	0.301	8000
	0.346	0.359			0.303	0.333	
	0.329	0.345			0.308	0.311	
W0	0.329	0.331	5970	YA	0.311	0.293	8000
VVO	0.317	0.320	3910	IA	0.290	0.270	8000
	0.316	0.333			0.283	0.284	

[•] Tolerance on each color bin (x, y) is ± 0.01

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Bins

Warm White Bin Structure

Bin Code	х	у	Typ. CCT (K)	Bin Code	х	у	Typ. CCT (K)
·	0.453	0.416			0.409	0.400	
MO	0.444	0.399	2770	Q0	0.402	0.382	3370
IVIO	0.459	0.403	2110	QU	0.416	0.389	3370
	0.467	0.419			0.424	0.407	
	0.460	0.430			0.414	0.414	
M1	0.453	0.416	2770	Q1	0.409	0.400	3370
IVII	0.467	0.419	2110	Qı	0.424	0.407	3370
	0.473	0.432			0.430	0.421	
	0.438	0.412			0.392	0.391	
N0	0.429	0.394	2950	R0	0.387	0.374	3650
140	0.444	0.399	2550	110	0.402	0.382	3030
	0.453	0.416			0.409	0.400	
	0.444	0.426			0.414	0.414	
N1	0.438	0.412	2950	R1	0.409	0.400	3650
111	0.453	0.416	2930	IXI	0.392	0.391	3030
	0.460	0.430			0.397	0.406	
	0.424	0.407			0.392	0.391	
P0	0.416	0.389	3150	S0	0.387	0.374	3950
10	0.429	0.394	3130	30	0.374	0.366	3930
	0.438	0.412			0.378	0.382	
	0.430	0.421			0.397	0.406	
P1	0.424	0.407	3150	S1	0.392	0.391	3950
	0.438	0.412	3130	01	0.378	0.382	3330
	0.444	0.426			0.382	0.397	

[•] Tolerance on each color bin (x, y) is ± 0.01

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Dominant Wavelength Bin Structure

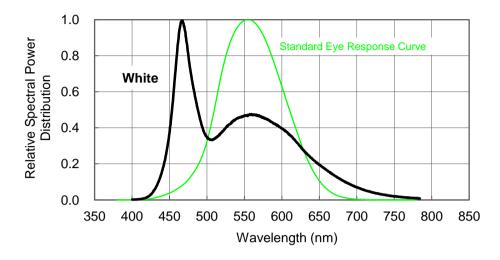
Color	Bin Code	Minimum Dominant Wavelength (nm)	Maximum Dominant Wavelength (nm)
Red	2	613.5	620.5
Reu	4	620.5	631.0
	2	587.0	589.5
Amber	4	589.5	592.0
Ambei	6	592.0	594.5
	7	594.5	597.0
	А	515	520
Green	1	520	525
Green	2	525	530
	3	530	535
	А	495	500
Cyon	1	500	505
Cyan	2	505	510
	3	510	515
	А	455	460
Pluo	1	460	465
Blue	2	465	470
	3	470	475

[•] ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.

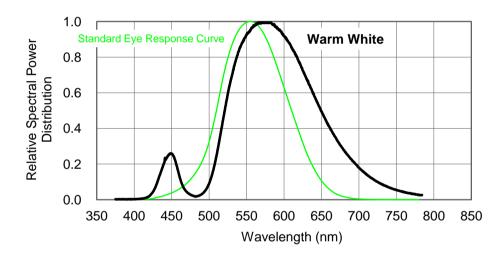
Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Spectrum, $T_J = 25^{\circ}C$

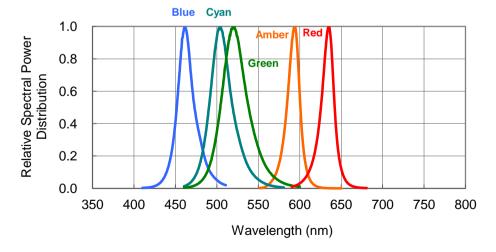
1. White



2. Warm White



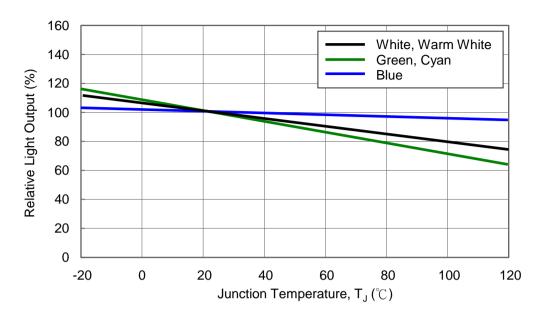
3. Blue · Cyan · Green · Amber · Red

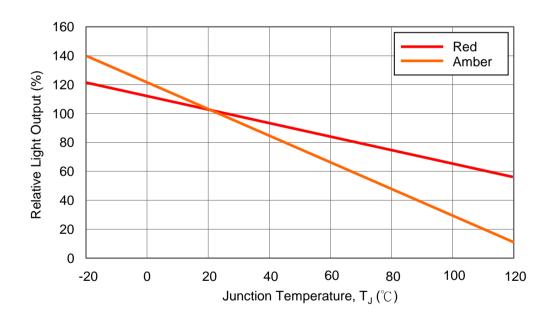


ProLight

Light Output Characteristics

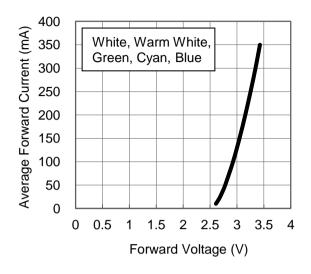
Relative Light Output vs. Junction Temperature at 350mA

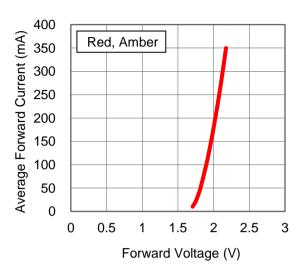




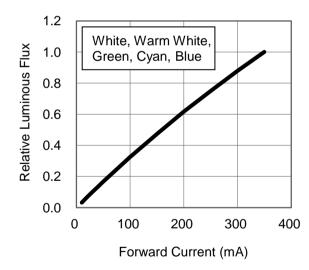
Forward Current Characteristics, T_J = 25°C

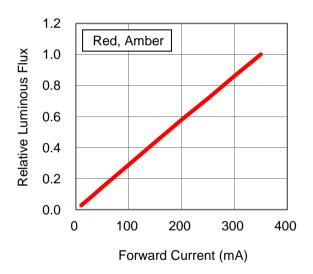
1. Forward Voltage vs. Forward Current





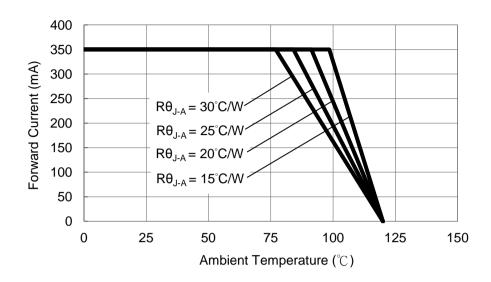
2. Forward Current vs. Normalized Relative Luminous Flux



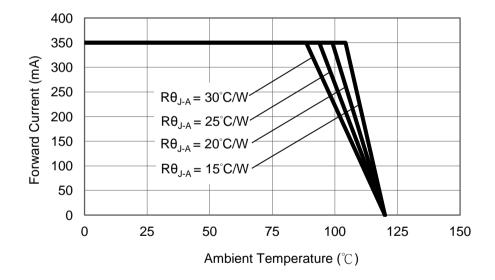


Ambient Temperature vs. Maximum Forward Current

1. White, Warm White, Green, Cyan, Blue (T_{JMAX} = 120°C)

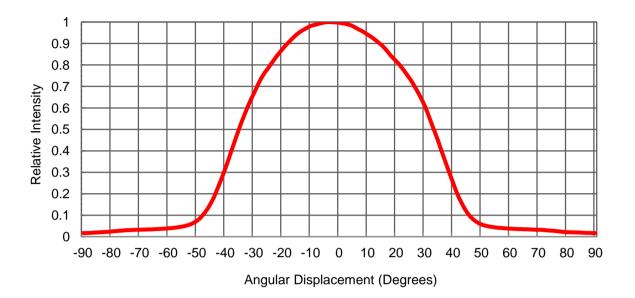


2. Red, Amber $(T_{JMAX} = 120$ °C)



Typical Representative Spatial Radiation Pattern

Dome Radiation Pattern



Moisture Sensitivity Level - JEDEC 2a

			Soak Requirements			
Level	Floo	r Life	Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions
20	4 wooks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /
2a 4 weeks	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH	

- The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.
- Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

				Soak Req	uirements		
Level	Floor	r Life	Stan	Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA	
'	Ormirinod	85% RH	100 10/ 0	85% RH	147 (10/1	
2	1 year	≤30°C /	168 +5/-0	85°C /	NA	NA	
۷	i yeai	60% RH	100 +5/-0	60% RH	INA	INA	
2a	4 weeks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /	
Za	4 Weeks	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH	
3	168 hours	≤30°C /	192 +5/-0	30°C /	40 +1/-0	60°C /	
3	100 110015	60% RH	192 +5/-0	60% RH	40 +1/-0	60% RH	
4	72 hours	≤30°C /	96 +2/-0	30°C /	20 +0.5/-0	60°C /	
	72 110013	60% RH	30 +2/-0	60% RH	20 +0.5/-0	60% RH	
5	48 hours	≤30°C /	72 +2/-0	30°C /	15 +0.5/-0	60°C /	
	40 110013	60% RH	7 Z +2/-0	60% RH	13 +0.5/-0	60% RH	
5a	24 hours	≤30°C /	48 +2/-0	30°C /	10 +0.5/-0	60°C /	
Ja	24 Hours	60% RH	40 +2/-0	60% RH	10 +0.5/-0	60% RH	
6	Time on Label	≤30°C /	Time on Label	30°C /	NA	NA	
	(TOL)	60% RH	(TOL)	60% RH	INA	INA	

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria	
Room Temperature	25°C, I _F = max DC (Note 1)	1000 hours	Note 2	
Operating Life (RTOL)	, 1			
Wet High Temperature	85°C/60%RH, I _F = max DC (Note 1)	1000 hours	Note 2	
Operating Life (WHTOL)				
Wet High Temperature	85°C/85%RH, non-operating	1000 hours	Note 2	
Storage Life (WHTSL)	oo o/oo/man, non operating	1000 110013	NOIC Z	
High Temperature	110°C, non-operating	1000 hours	Note 2	
Storage Life (HTSL)	110 C, Hon-operating	1000 110015	Note 2	
Low Temperature	-40°C, non-operating	1000 hours	Note 2	
Storage Life (LTSL)	-40 C, non-operating	1000 110015	NOIE Z	
Non-operating	-40°C to 120°C, 30 min. dwell,	200 cycles	Note 2	
Temperature Cycle (TMCL)	<5 min. transfer	200 Cycles	Note 2	
Non-operating	-40°C to 120°C, 20 min. dwell,	200 cycles	Note 2	
Thermal Shock (TMSK)	<20 sec. transfer	200 cycles	Note 2	
Mechanical Shock	1500 G, 0.5 msec. pulse,		Note 3	
Wechanical Shock	5 shocks each 6 axis		Note 3	
Natural Drop	On concrete from 1.2 m, 3X		Note 3	
Variable Vibration	10-2000-10 Hz, log or linear sweep rate,		Note 2	
Frequency	20 G about 1 min., 1.5 mm, 3X/axis		Note 3	
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3	
Solderability	Steam age for 16 hrs., then solder dip		Solder coverage	
Joiderability	at 260°C for 5 sec.		on lead	

Notes:

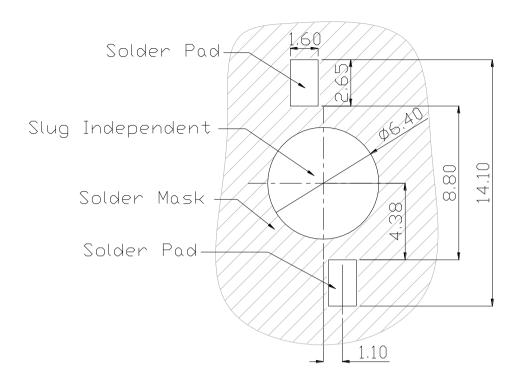
- 1. Depending on the maximum derating curve.
- 2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement		
item	rest Condition	Min.	Max.	
Forward Voltage (V _F)	I _F = max DC		Initial Level x 1.1	
Luminous Flux or Radiometric Power (Φ_V)	I _F = max DC	Initial Level x 0.7		
Reverse Current (I _R)	V _R = 5V		50 μA	

^{*} The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

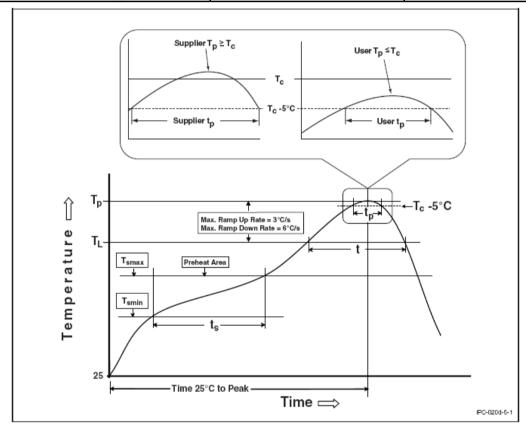
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

Reflow Soldering Condition

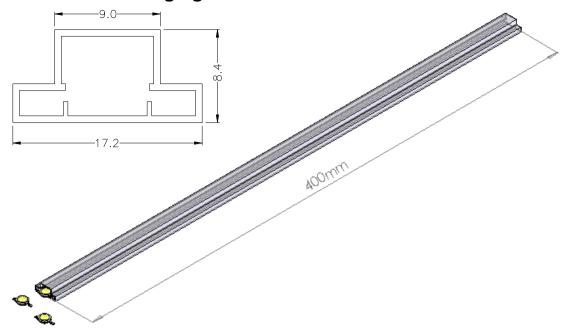
Profile Feature	Sn-Pb Eutectic Assembly	Low-Temp. & Pb-Free Assembly (58Bi-42Sn Eutectic Alloy)
Preheat & Soak		
Temperature min (T _{smin})	100 °C	90 °C
Temperature max (T _{smax})	150 °C	120 °C
Time (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Average Ramp-Up Rate $(T_{smax} \text{ to } T_P)$	3 °C / second max.	2 °C / second max.
Liquidous temperature (T _L)	183°C	138°C
Time at liquidous (t _L)	60-150 seconds	20-50 seconds
Peak package body temperature (T _P)	235°C	185°C
Time (t _P) within 5°C of the specified	20 seconds	20 seconds
classification temperature (T _C)		
Average ramp-down rate (T _P to T _{smax})	6 °C/second max.	3 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	4 minutes max.



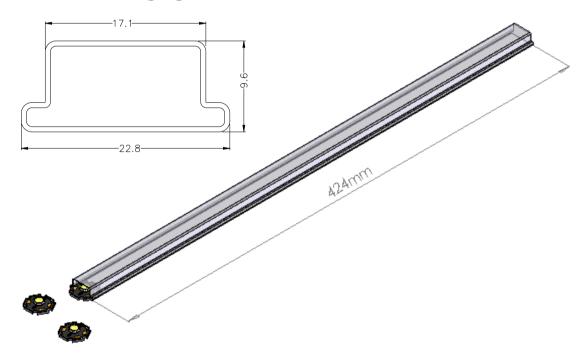
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

ProLight

Emitter Tube Packaging



Star Tube Packaging



Notes:

- 1. Emitter 50 pieces per tube and Star 20 pieces per tube.
- 2. Drawing not to scale.
- 3. All dimensions are in millimeters.
- 4. All dimendions without tolerances are for reference only.

^{**}Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

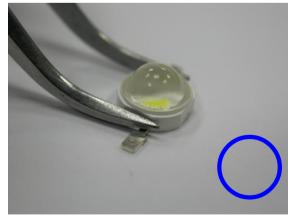
- Storage
 - Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)





ProLight